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74AUP1G98
TinyLogic® Low Power Universal Configurable Two-Input Logic Gate

Features

- 0.8V to 3.6V V_{CC} Supply Operation
- 3.6V Over-Voltage Tolerant I/Os at V_{CC} from 0.8V to 3.6V
- High Speed t_{PD}
  - 3.0ns: Typical at 3.3V
- Power-Off High-Impedance Inputs and Outputs
- Low Static Power Consumption
  - I_{CC}=0.9µA Maximum
- Low Dynamic Power Consumption
  - C_{PD}=2.5pF Typical at 3.3V
- Ultra-Small MicroPak™ Packages

Description

The 74AUP1G98 is a universal configurable 2-input logic gate that provides a high performance and low power solution ideal for battery-powered portable applications. This product is designed for a wide low voltage operating range (0.8V to 3.6V) and guarantees very low static and dynamic power consumption across the entire voltage range. All inputs are implemented with hysteresis to allow for slower transition input signals and better switching noise immunity.

The 74AUP1G98 provides for multiple functions as determined by various configurations of the three inputs. The potential logic functions provided are MUX, AND, OR, NAND, and NOR, inverter and buffer. Refer to Figures 5 to 11.

Ordering Information

Part Number	Top Mark	Package	Packing Method
74AUP1G98L6X	AE	6-Lead Micropak™, 1.0mm Wide	5000 Units on Tape & Reel
74AUP1G98FHX	AE	6-Lead, MicroPak2™, 1x1mm Body, .35mm Pitch	5000 Units on Tape & Reel

Logic Diagram

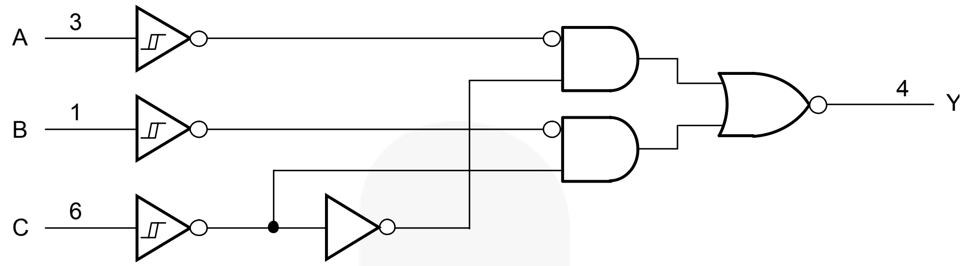


Figure 1. Logic Diagram (Positive Logic)

Pin Configurations

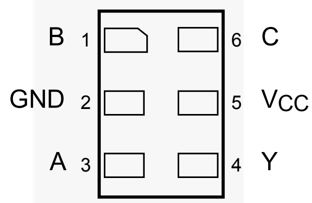


Figure 2. MicroPak™ (Top Through View)

Pin Definitions

Pin # MicroPak™	Name	Description
1	B	Data Input
2	GND	Ground
3	A	Data Input
4	Y	Output
5	V_{CC}	Supply Voltage
6	C	Data Input

Function Table

Inputs			74AUP1G98
C	B	A	Y=Output
L	L	L	H
L	L	H	H
L	H	L	L
L	H	H	L
H	L	L	H
H	L	H	L
H	H	L	H
H	H	H	L

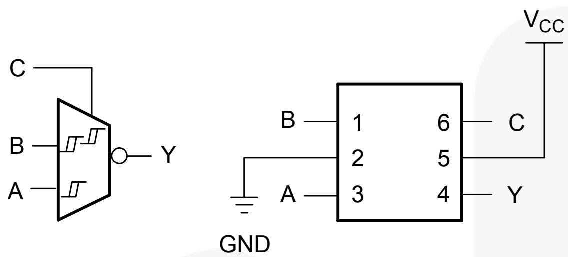
H = HIGH Logic Level
L = LOW Logic Level

Function Selection Table

2-Input Logic Function	Connection Configuration
2-to-1 MUX with Inverted Output	Figure 3
2-Input NAND Gate	Figure 4
2-Input NOR Gate with One Inverted Input	Figure 5
2-Input AND Gate with One Inverted Input	Figure 5
2-Input NAND Gate with One Inverted Input	Figure 6
2-Input OR Gate with One Inverted Input	Figure 6
2-Input NOR Gate	Figure 7
Buffer	Figure 8
Inverter	Figure 9

74AUP1G98 Logic Configurations

Figure 3 through Figure 9 show the logical functions that can be implemented using the 74AUP1G98. The diagrams show the DeMorgan's equivalent logic duals for a given two-input function. The logical implementation is next to the board-level physical implementation of how the pins of the function should be connected.



Note:
1. When C is L, Y=$\overline{B}$.
2. When C is H, Y=$\overline{A}$.

Figure 3. 2-to-1 MUX with Inverted Output

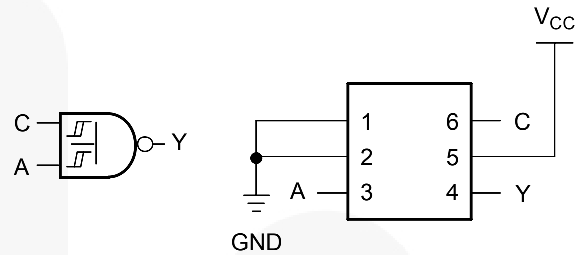


Figure 4. 2-Input NAND Gate

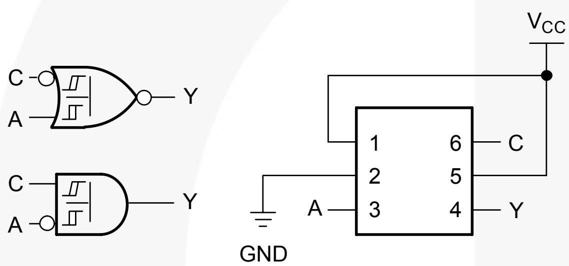


Figure 5. Input NOR Gate with One Inverted Input 2-Input AND Gate with One Inverted Input

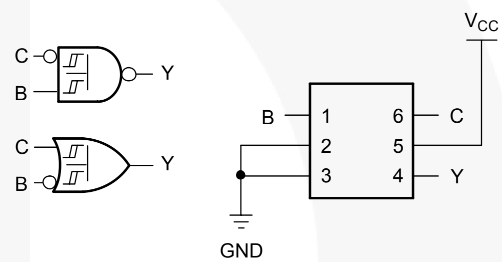


Figure 6. 2-Input NAND Gate with One Inverted Input 2-Input OR Gate with One Inverted Input

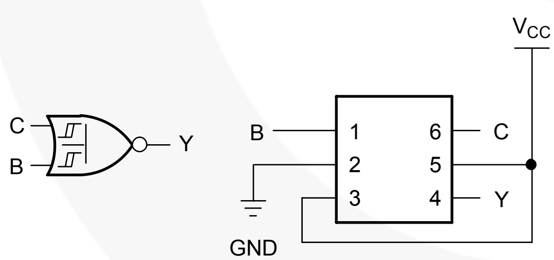


Figure 7. 2-Input NOR Gate

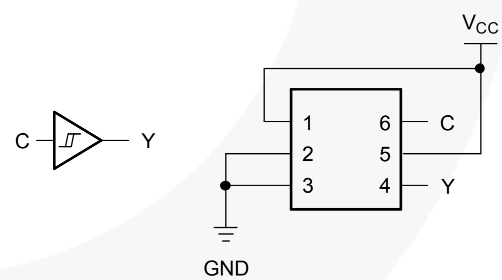


Figure 8. Buffer

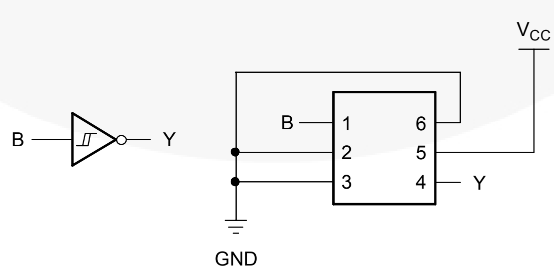


Figure 9. Inverter

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter		Min.	Max.	Unit
V_{CC}	Supply Voltage		-0.5	4.6	V
V_{IN}	DC Input Voltage		-0.5	4.6	V
V_{OUT}	DC Output Voltage	HIGH or LOW State(3)	-0.5	V_{CC} + 0.5	V
		V_{CC}=0V	-0.5	4.6	
I_{IK}	DC Input Diode Current	V_{IN} < 0V		-50	mA
I_{OK}	DC Output Diode Current	V_{OUT} < 0V		-50	mA
		V_{OUT} > V_{CC}		+50	
I_{OH} / I_{OL}	DC Output Source / Sink Current			±50	mA
I_{CC} or I_{GND}	DC V_{CC} or Ground Current per Supply Pin			±50	mA
T_{STG}	Storage Temperature Range		-65	+150	°C
T_J	Junction Temperature Under Bias			+150	°C
T_L	Junction Lead Temperature, Soldering 10s			+260	°C
	Power Dissipation at +85°C	MicroPak-6		130	mW
		MicroPak2-6		120	
ESD	Human Body Model, JEDEC:JESD22-A114			5000+	V
	Charged Device Model, JEDEC:JESD22-C101			2000	

Note:

3. I_O absolute maximum rating must be observed.

Recommended Operating Conditions[4]

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Conditions	Min.	Max.	Unit
V_{CC}	Supply Voltage		0.8	3.6	V
V_{IN}	Input Voltage		0	3.6	V
V_{OUT}	Output Voltage	V_{CC}=0V	0	3.6	V
		HIGH or LOW State	0	V_{CC}	
I_{OH}/I_{OL}	Output Current	V_{CC}=3.0V to 3.6V		±4.0	mA
		V_{CC}=2.3V to 2.7V		±3.1	
		V_{CC}=1.65V to 1.95V		±1.9	
		V_{CC}=1.4V to 1.6V		±1.7	
		V_{CC}=1.1V to 1.3V		±1.1	
		V_{CC}=0.8V		±20.0	μA
T_A	Operating Temperature, Free Air		-40	+85	°C
	Thermal Resistance	MicroPak-6		500	
		MicroPak2-6		560	

Note:

4. Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Symbol	Parameter	V_{CC}	Conditions	T_A=25°C		T_A=-40 to 85°C		Units
				Min.	Max.	Min.	Max.	
V_P	Positive Threshold Voltage	0.80		0.30	0.60	0.30	0.60	V
		1.10		0.53	0.90	0.53	0.90	
		1.40		0.74	1.11	0.74	1.11	
		1.65		0.91	1.29	0.91	1.29	
		2.30		1.37	1.77	1.37	1.77	
		3.00		1.88	2.29	1.88	2.29	
V_N	Negative Threshold Voltage	0.80		0.10	0.60	0.10	0.60	V
		1.10		0.26	0.65	0.26	0.65	
		1.40		0.39	0.75	0.39	0.75	
		1.65		0.47	0.84	0.47	0.84	
		2.30		0.69	1.04	0.69	1.04	
		3.00		0.88	1.24	0.88	1.24	
V_H	Hysteresis Voltage	0.80		0.07	0.50	0.07	0.50	V
		1.10		0.08	0.46	0.08	0.46	
		1.40		0.18	0.56	0.18	0.56	
		1.65		0.27	0.66	0.27	0.66	
		2.30		0.53	0.92	0.53	0.92	
		3.00		0.79	1.31	0.79	1.31	
V_{OH}	HIGH Level Output Voltage	$0.80 \le V_{CC} \le 3.60$	I_{OH}=-20µA	V_{CC}-0.1		V_{CC}-0.1		V
		$1.10 \le V_{CC} \le 1.30$	I_{OH}=-1.1mA	0.75 x V_{CC}		0.70 x V_{CC}		
		$1.40 \le V_{CC} \le 1.60$	I_{OH}=-1.7mA	1.11		1.03		
		$1.65 \le V_{CC} \le 1.95$	I_{OH}=-1.9mA	1.32		1.30		
		$2.30 \le V_{CC} \le 2.70$	I_{OH}=-2.3mA	2.05		1.97		
			I_{OH}=-3.1mA	1.90		1.85		
		$3.00 \le V_{CC} \le 3.60$	I_{OH}=-2.7mA	2.72		2.67		
			I_{OH}=-4.0mA	2.60		2.55		
V_{OL}	LOW Level Output Voltage	$0.80 \le V_{CC} \le 3.60$	I_{OL}=20µA		0.10		0.10	V
		$1.10 \le V_{CC} \le 1.30$	I_{OL}=1.1mA		0.30 x V_{CC}		0.30 x V_{CC}	
		$1.40 \le V_{CC} \le 1.60$	I_{OL}=1.7mA		0.31		0.37	
		$1.65 \le V_{CC} \le 1.95$	I_{OL}=1.9mA		0.31		0.35	
		$2.30 \le V_{CC} \le 2.70$	I_{OL}=2.3mA		0.31		0.33	
			I_{OL}=3.1mA		0.44		0.45	
		$2.70 \le V_{CC} \le 3.60$	I_{OL}=2.7mA		0.31		0.33	
			I_{OL}=4.0mA		0.44		0.45	
I_{IN}	Input Leakage Current	0V to 3.6V	$0 \le V_{IN} \le 3.6$		±0.1		±0.5	µA
I_{OFF}	Power Off Leakage Current	0V	$0 \le (V_{IN}, V_O) \le 3.6$		0.2		0.6	µA
ΔI_{OFF}	Additional Power Off Leakage Current	0V to 0.2V	V_{IN} or V_O=0V to 3.6V		0.2		0.6	µA
I_{CC}	Quiescent Supply Current	0.8V to 3.6V	V_{IN} - V_{CC} or GND		0.5		0.9	µA
			$V_{CC} \le V_{IN} \le 3.6$				±0.9	
ΔI_{CC}	Increase in I_{CC} per Input	3.3V	V_{IN}=V_{CC} -0.6V		40.0		50.0	µA

AC Electrical Characteristics

Symbol	Parameter	V_{CC}	Conditions	T_A=25°C			T_A=-40 to 85°C		Units	Figure
				Min.	Typ.	Max.	Min.	Max.		
t_{PHL}, t_{PLH}	Propagation Delay	0.80	C_L=5pF, R_L=1MΩ		25.3				ns	Figure 10 Figure 11
		$1.10 \le V_{CC} \le 1.30$		2.9	8.7	12.9	2.7	13.2		
		$1.40 \le V_{CC} \le 1.60$		2.4	5.1	7.7	2.4	8.3		
		$1.65 \le V_{CC} \le 1.95$		2.2	4.4	6.3	1.9	7.0		
		$2.30 \le V_{CC} \le 2.70$		2.0	3.5	4.8	1.8	5.4		
		$3.00 \le V_{CC} \le 3.60$		1.5	3.1	4.2	1.5	4.5		
		0.80	C_L=10pF, R_L=1MΩ		26.7					
		$1.10 \le V_{CC} \le 1.30$		3.3	8.5	14.5	3.0	15.1		
		$1.40 \le V_{CC} \le 1.60$		2.7	5.8	8.8	2.8	9.5		
		$1.65 \le V_{CC} \le 1.95$		2.5	4.7	7.2	2.3	8.0		
		$2.30 \le V_{CC} \le 2.70$		1.9	3.6	5.3	1.9	5.9		
		$3.00 \le V_{CC} \le 3.60$		1.5	3.1	4.7	1.5	4.9		
		0.80	C_L=15pF, R_L=1MΩ		29.8					
		$1.10 \le V_{CC} \le 1.30$		3.6	9.9	16.1	3.3	16.9		
		$1.40 \le V_{CC} \le 1.60$		3.0	6.2	9.7	3.1	10.5		
		$1.65 \le V_{CC} \le 1.95$		2.8	5.3	7.9	2.5	8.9		
		$2.30 \le V_{CC} \le 2.70$		2.5	4.1	5.9	2.5	6.6		
		$3.00 \le V_{CC} \le 3.60$		1.7	3.3	5.2	1.7	5.5		
		0.80	C_L=30pF, R_L=1MΩ		27.5					
		$1.10 \le V_{CC} \le 1.30$		3.4	9.1	18.5	3.4	19.0		
		$1.40 \le V_{CC} \le 1.60$		3.1	5.7	10.5	3,1	11.0		
		$1.65 \le V_{CC} \le 1.95$		2.7	4.7	8.7	2.7	9.5		
		$2.30 \le V_{CC} \le 2.70$		1.7	3.5	6.5	1.7	7.1		
		$3.00 \le V_{CC} \le 3.60$		1.3	3.0	5.6	1.3	6.3		
C_{IN}	Input Capacitance	0			2.1				pF	
C_{OUT}	Output Capacitance	0			3.0				pF	
C_{PD}	Power Dissipation Capacitance	0.80	V_{IN}=0V or V_{CC}, f=10MHz		1.7				pF	
		$1.10 \le V_{CC} \le 1.30$			1.8					
		$1.40 \le V_{CC} \le 1.60$			1.81					
		$1.65 \le V_{CC} \le 1.95$			1.84					
		$2.30 \le V_{CC} \le 2.70$			2.1					
		$3.00 \le V_{CC} \le 3.60$			2.5					

AC Loadings and Waveforms

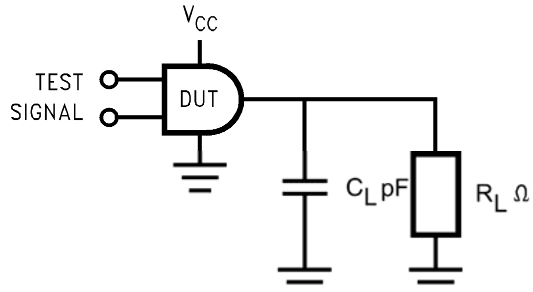


Figure 10. AC Test Circuit

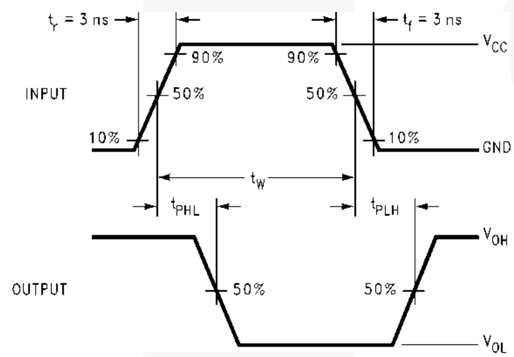
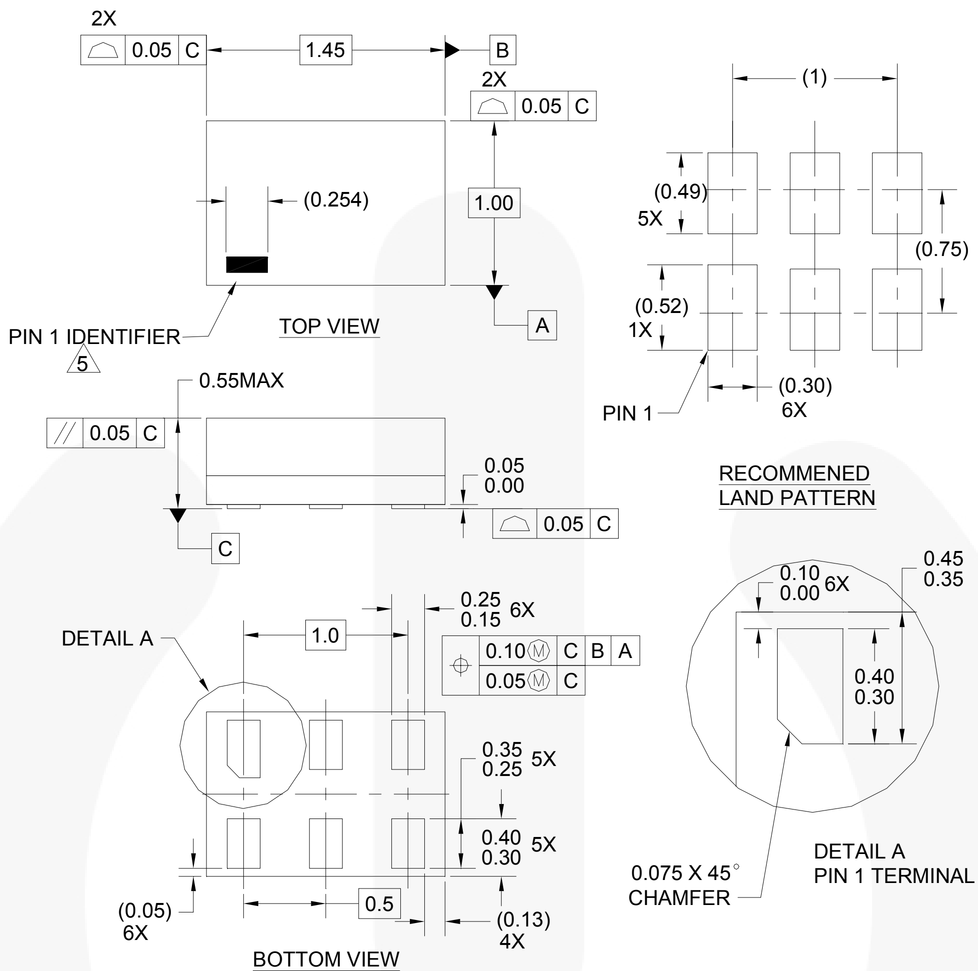


Figure 11. AC Waveforms

Symbol	V_{CC}					
	3.3V ± 0.3V	**2.5V ± 0.2V**	**1.8V ± 0.15V**	**1.5V ± 0.10V**	**1.2V ± 0.10V**	**0.8V**
V_{mi}	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_{mo}	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$

Physical Dimensions



Notes:

1. CONFORMS TO JEDEC STANDARD M0-252 VARIATION UAAD
2. DIMENSIONS ARE IN MILLIMETERS
3. DRAWING CONFORMS TO ASME Y14.5M-1994
4. FILENAME AND REVISION: MAC06AREV4
5. PIN ONE IDENTIFIER IS 2X LENGTH OF ANY OTHER LINE IN THE MARK CODE LAYOUT.

Figure 12. 6-Lead, MicroPak™, 1.0mm Wide

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Tape and Reel Specifications

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications: *http://www.fairchildsemi.com/products/logic/pdf/micropak_tr.pdf.*

Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
L6X	Leader (Start End)	125 (Typical)	Empty	Sealed
	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

Physical Dimensions

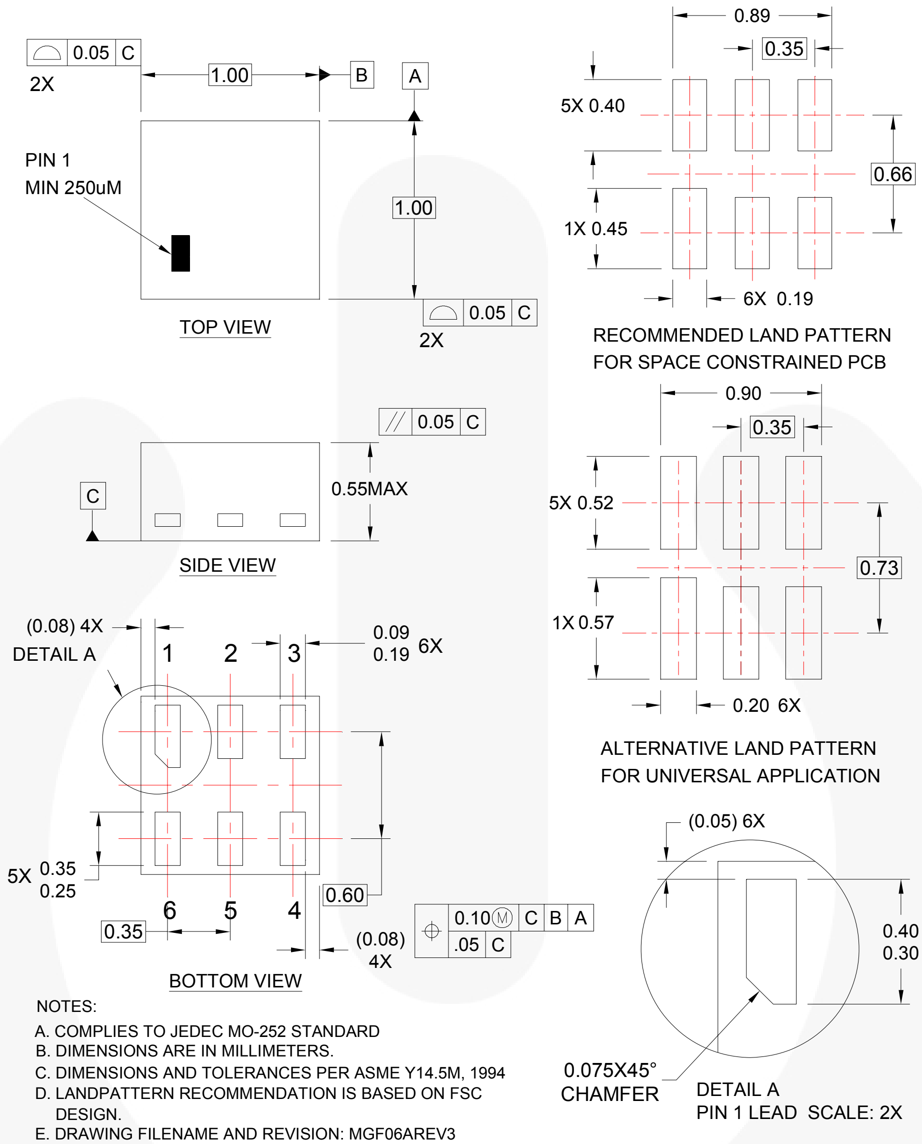

Figure 13. 6-Lead, MicroPak2, 1x1mm Body, .35mm Pitch

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Tape and Reel Specifications

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications: http://www.fairchildsemi.com/packaging/MicroPAK2_6L_tr.pdf.

Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
FHX	Leader (Start End)	125 (Typical)	Empty	Sealed
	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

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FPS™

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ISOPLANAR™
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TinyCalc™
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TinyPower™
TinyPWM™
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UniFET™
VCX™
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XS™

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2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

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PUBLICATION ORDERING INFORMATION

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For additional information, please contact your local Sales Representative